

Ligand-Exchange and Etching Reactions Between Metal Fluorides and Silane Precursors Containing Different Ligands

Ann Lii-Rosales, Virginia L. Johnson, Andrew S. Cavanagh, Andreas Fischer, Thorsten Lill, Sandeep Sharma, and Steven M. George

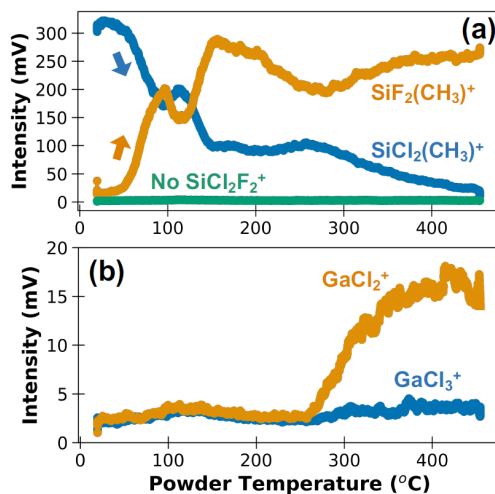


Figure 1. Ion intensities versus temperature during reaction between $\text{SiCl}_2(\text{CH}_3)_2$ and GaF_3 powder. (a) $\text{SiCl}_2(\text{CH}_3)_2$ precursor ($\text{SiCl}_2(\text{CH}_3)^+$), $\text{SiCl}_2(\text{CH}_3)_2$ precursor after complete F/Cl exchange ($\text{SiF}_2(\text{CH}_3)^+$), and $\text{SiCl}_2(\text{CH}_3)_2$ precursor after complete F/ CH_3 exchange ($\text{SiCl}_2\text{F}_2^+$, not observed). (b) Metal etch product GaCl_3^+ and its fragment GaCl_2^+ .

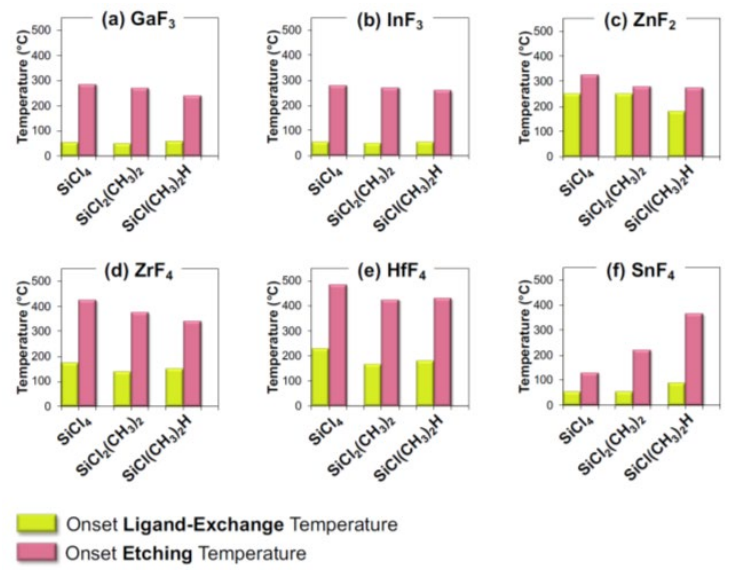


Figure 2. Onset temperatures for ligand exchange and metal etching observed for spontaneous etching of various metal fluorides using different silane precursors.